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(12) United States Design Patent
Parekh

(10) **Patent No.: US D816,623 S**
(45) **Date of Patent: ** *May 1, 2018**

(54) **SOLDER PAD**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/550,884**

(22) Filed: **Jan. 7, 2016**

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/120, 121, 133, 162, 179, 180, 182; D14/130, 486; D26/1; D15/144.2
CPC H05K 1/111-1/114
See application file for complete search history.

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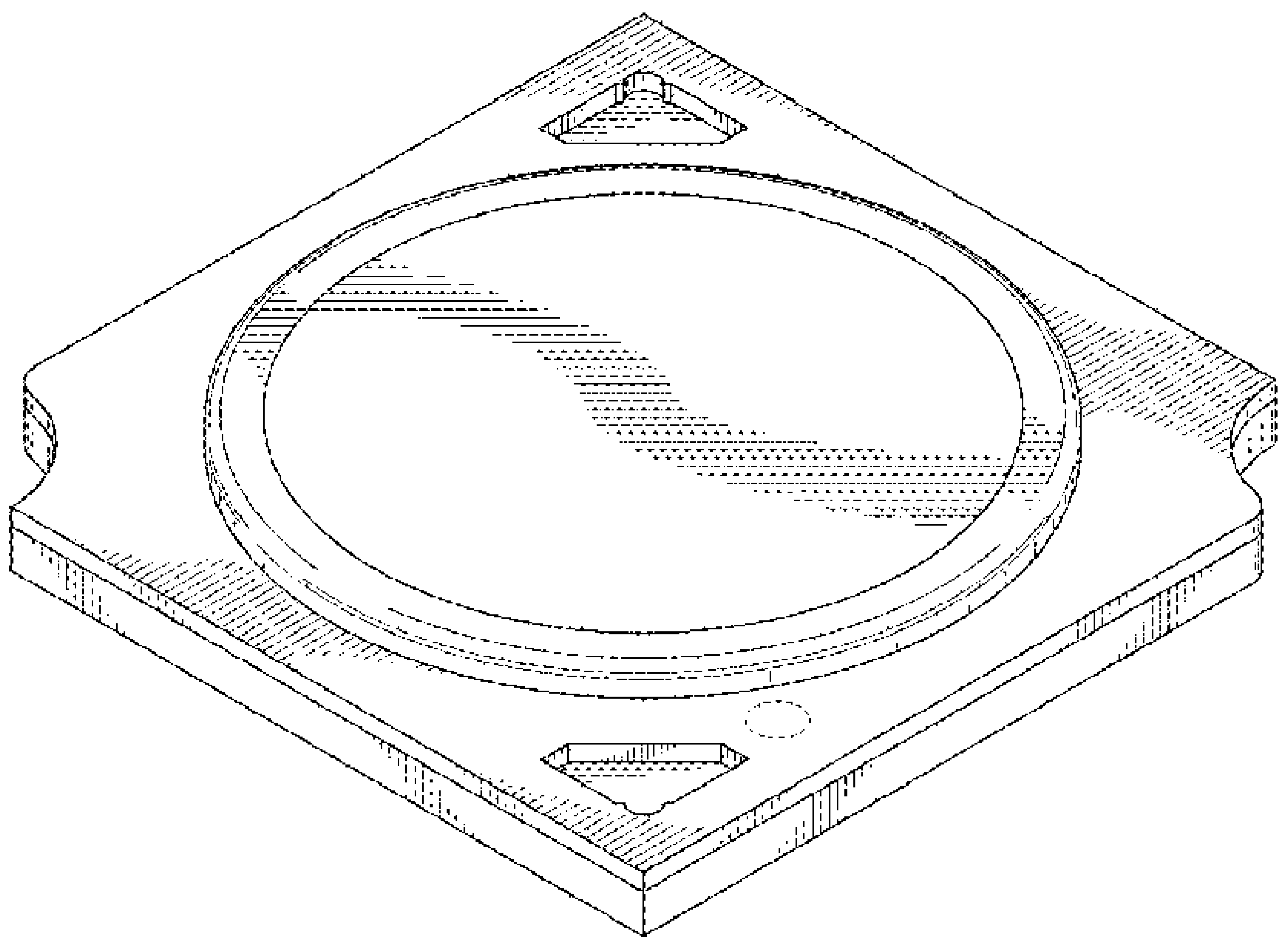
(57) **CLAIM**

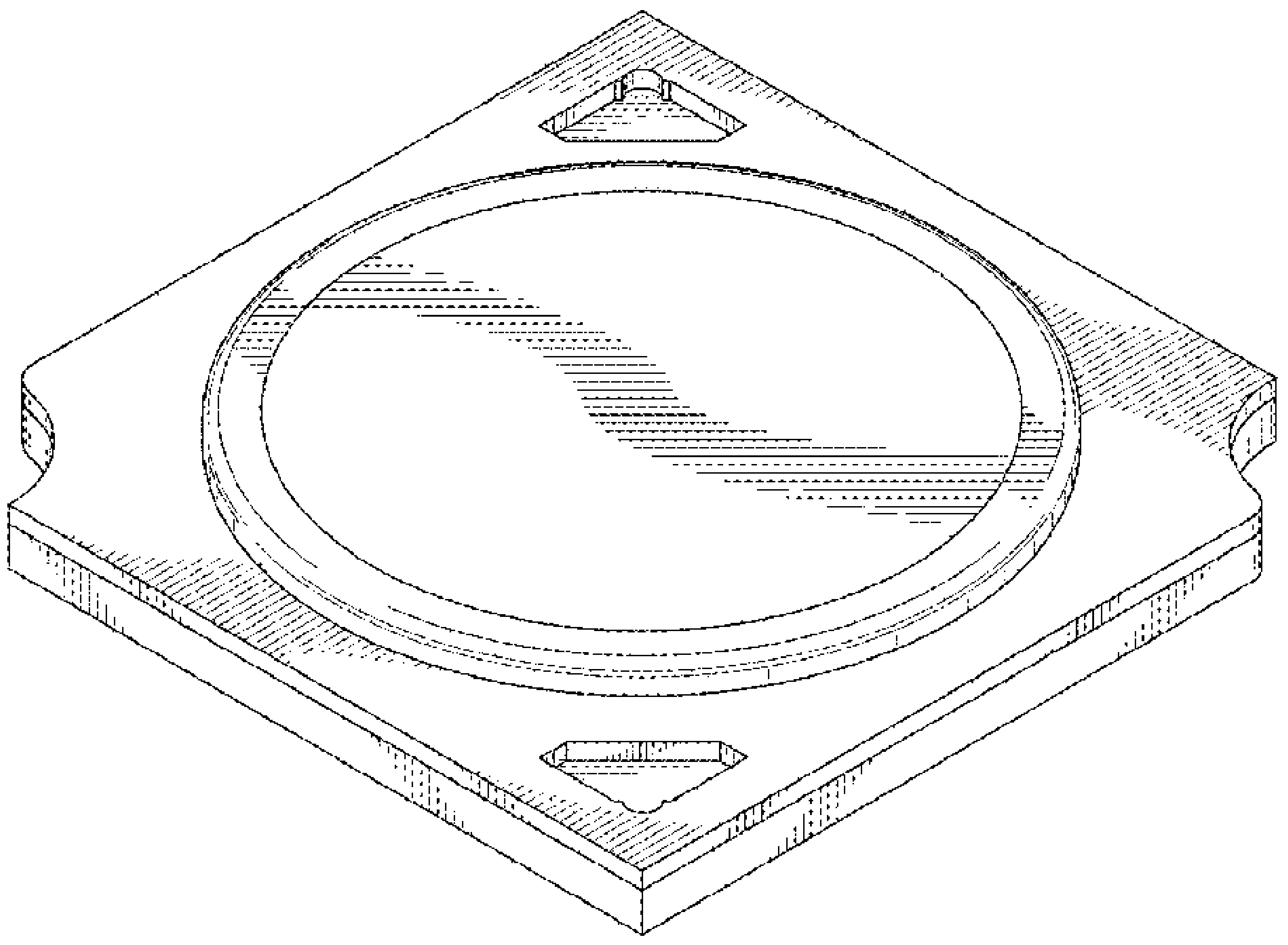
The ornamental design for a solder pad, as shown and described.

DESCRIPTION

FIG. **1** is a front, left, and top perspective view of a first embodiment of a solder pad in accordance with my design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a front elevation view thereof;
FIG. **4** is a rear elevation view thereof;
FIG. **5** is a left elevation view thereof; and
FIG. **6** is a right elevation view thereof;
FIG. **7** is a front, left, and top perspective view of a second embodiment of a solder pad in accordance with my design.
FIG. **8** is a top plan view thereof;
FIG. **9** is a front elevation view thereof;
FIG. **10** is a rear elevation view thereof;
FIG. **11** is a left elevation view thereof; and,
FIG. **12** is a right elevation view thereof.
All broken lines shown in the drawings depict portions of the solder pad that form no part of the claimed design.

1 Claim, 6 Drawing Sheets





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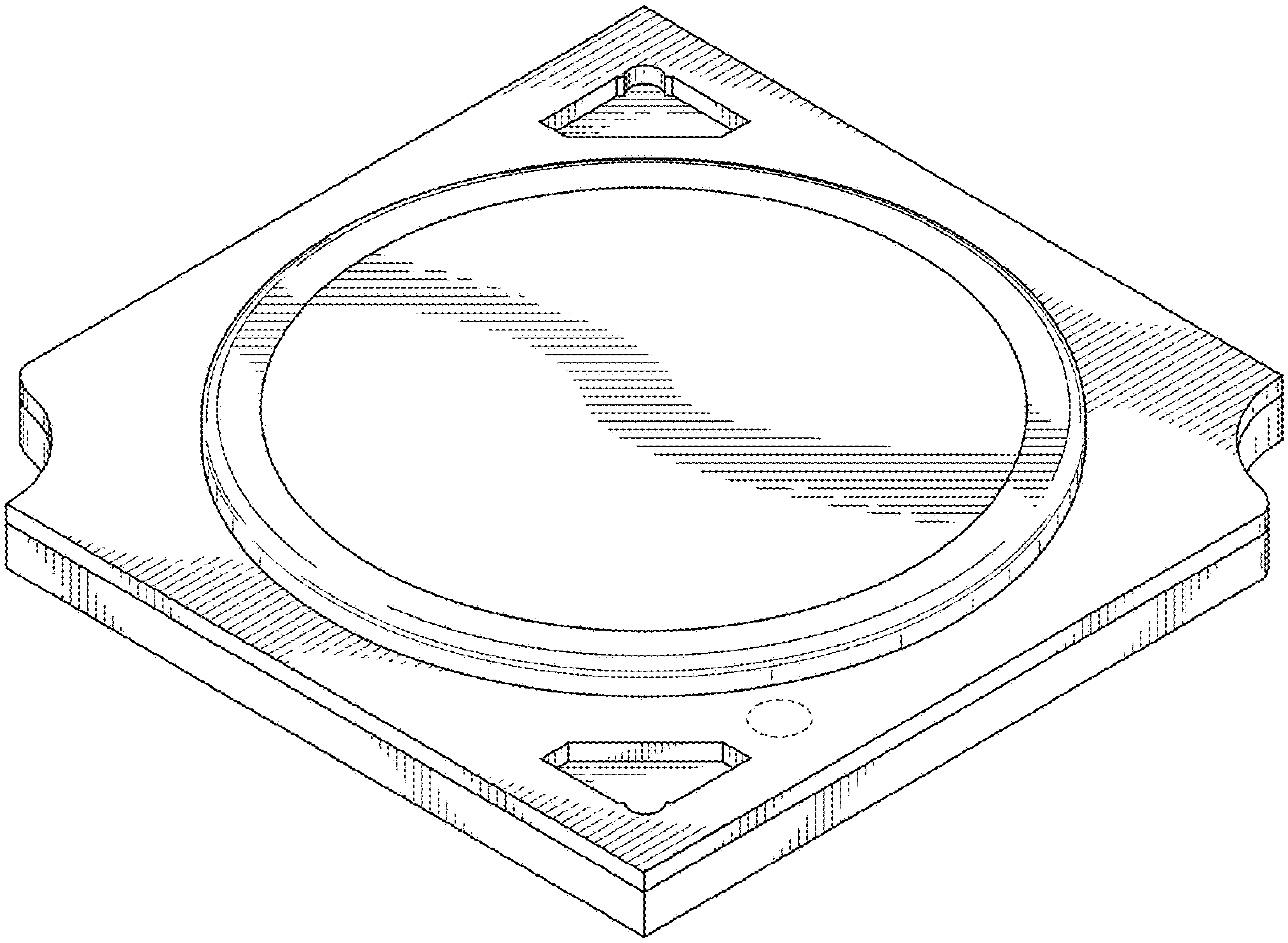

FIG. 1

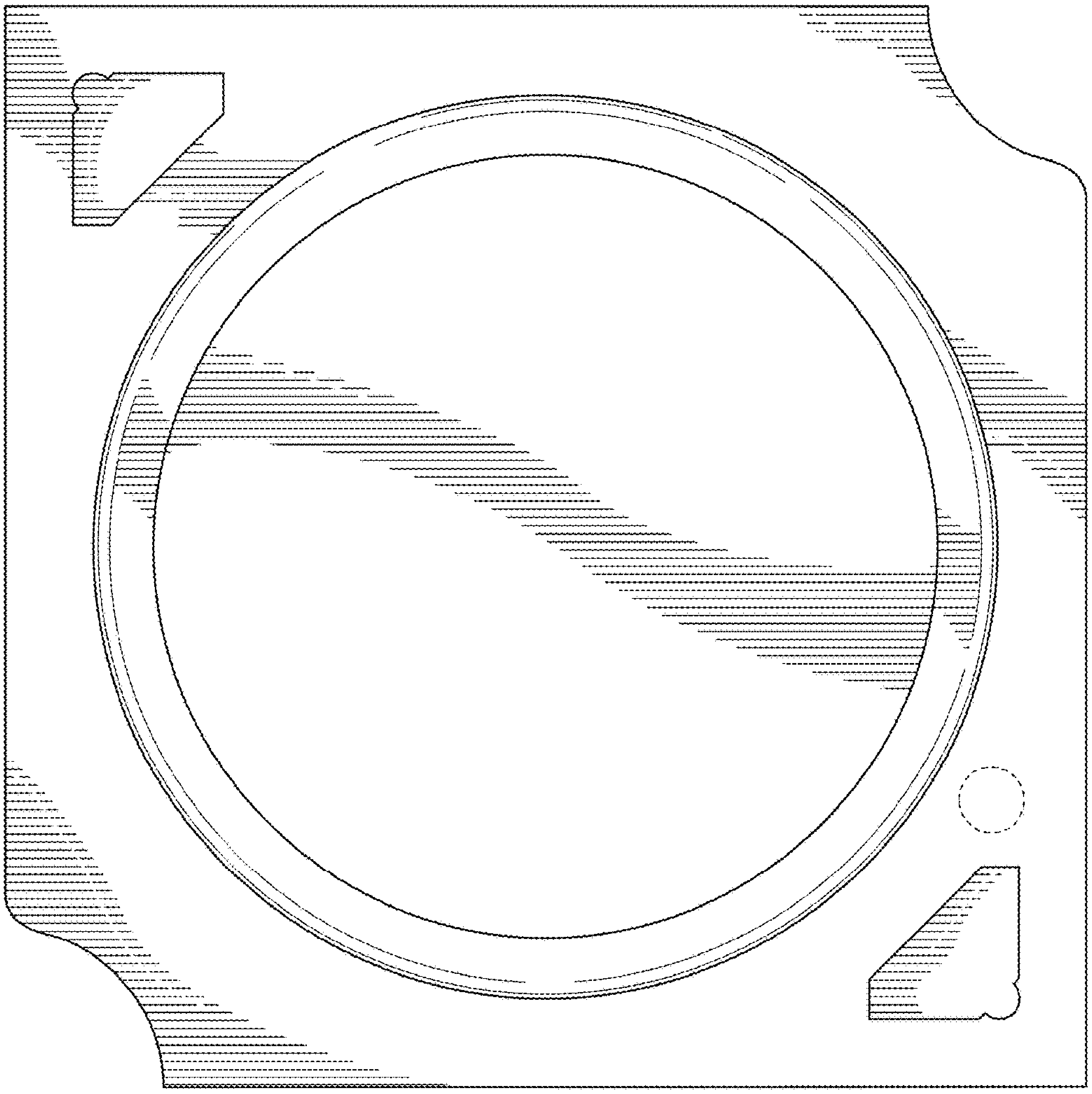

FIG. 2

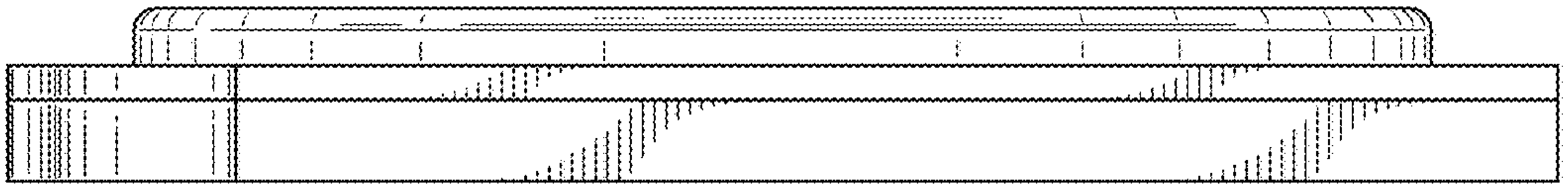

FIG. 3

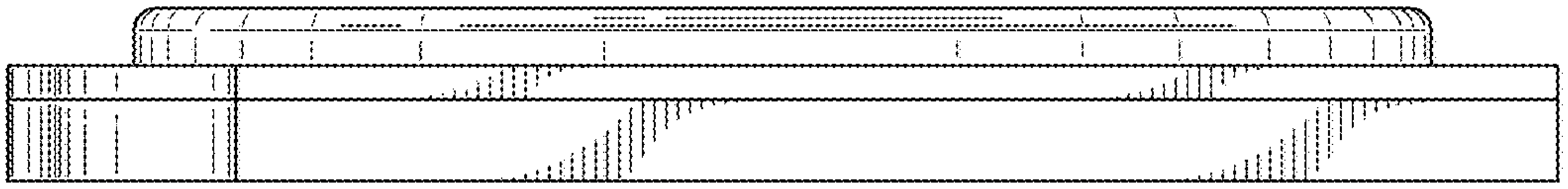

FIG. 4

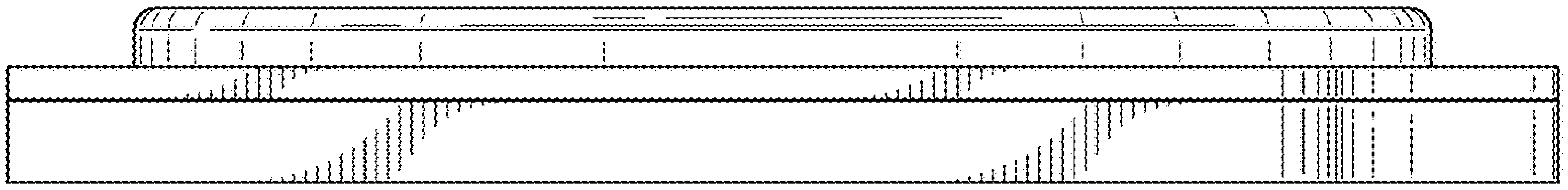

FIG. 5

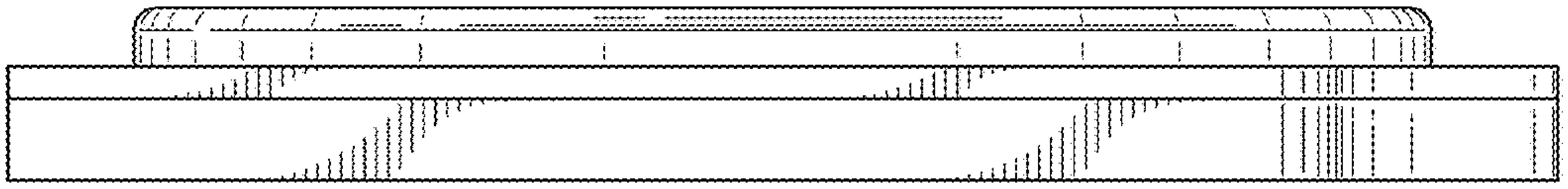

FIG. 6

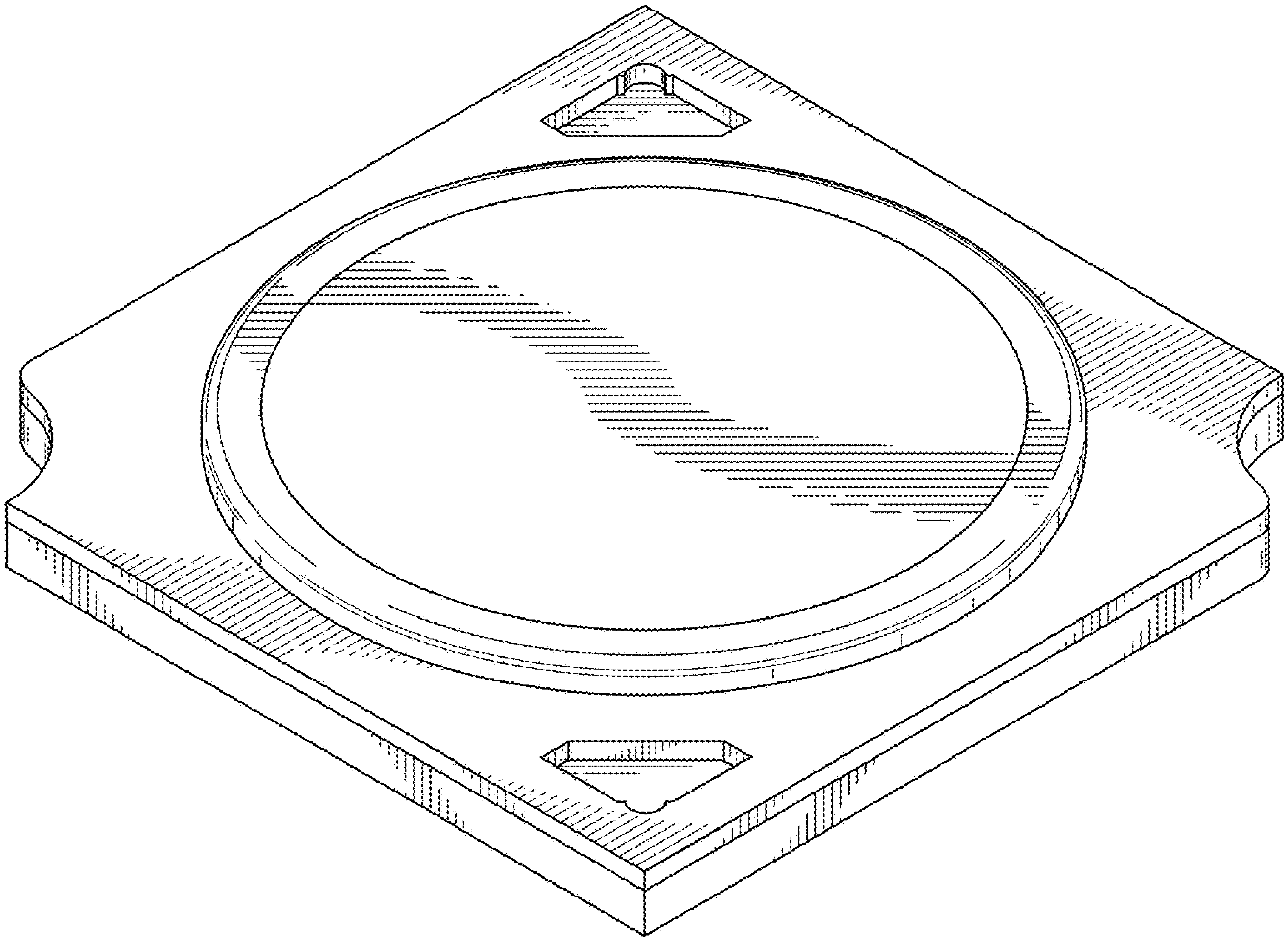

FIG. 7

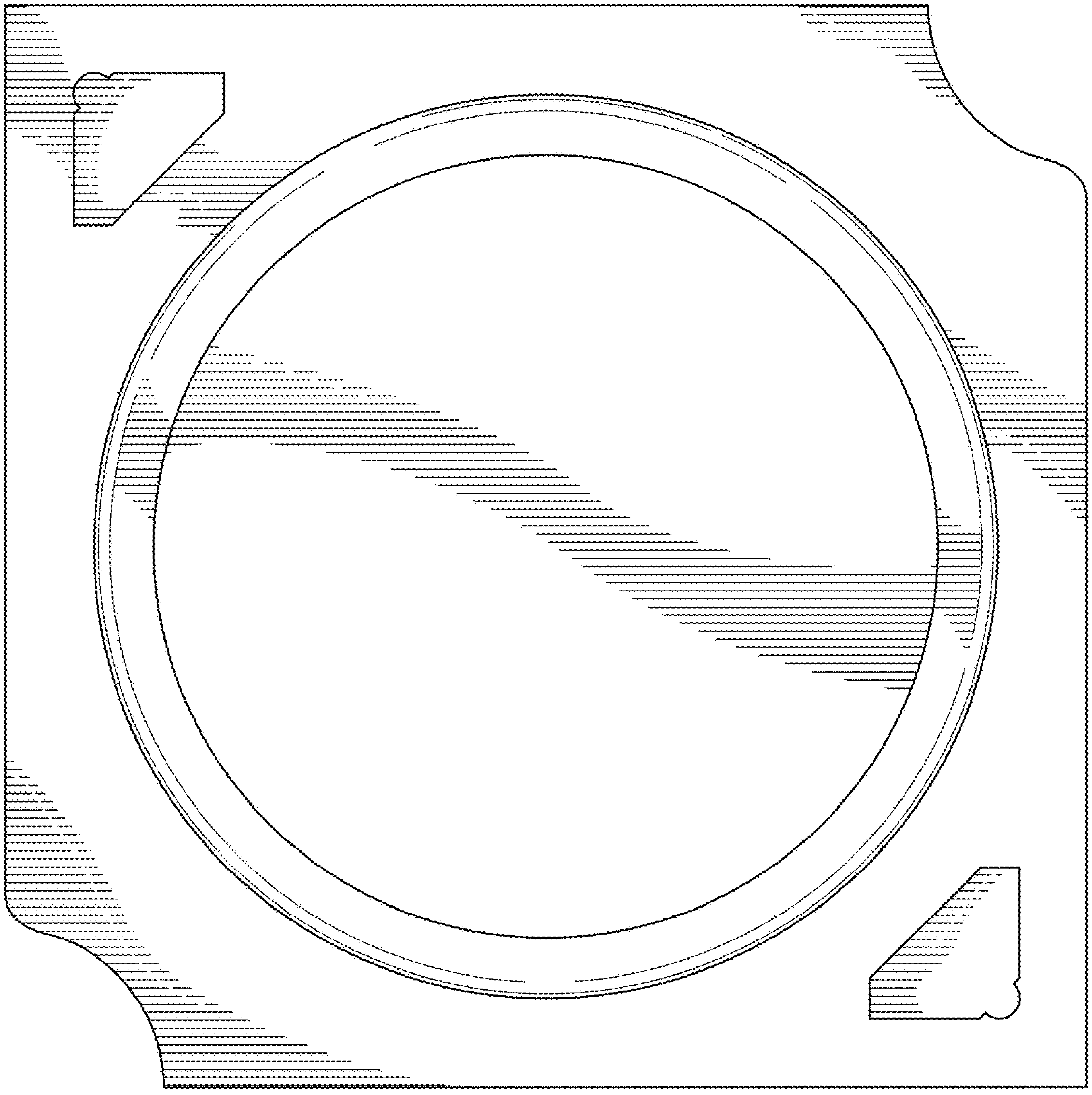

FIG. 8

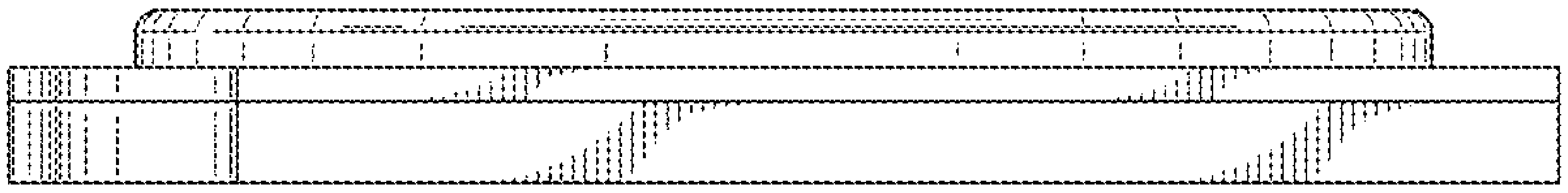

FIG. 9

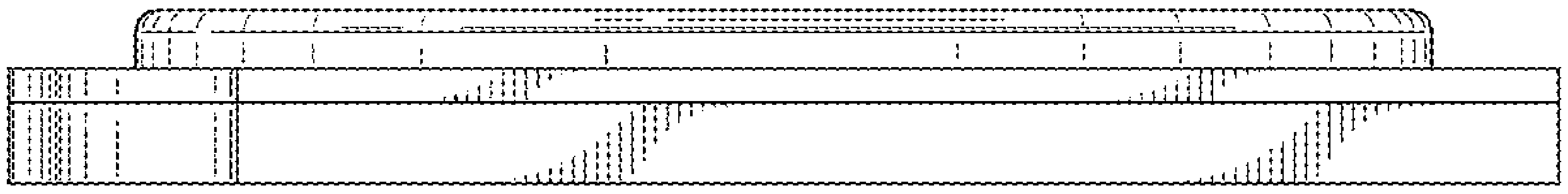

FIG. 10

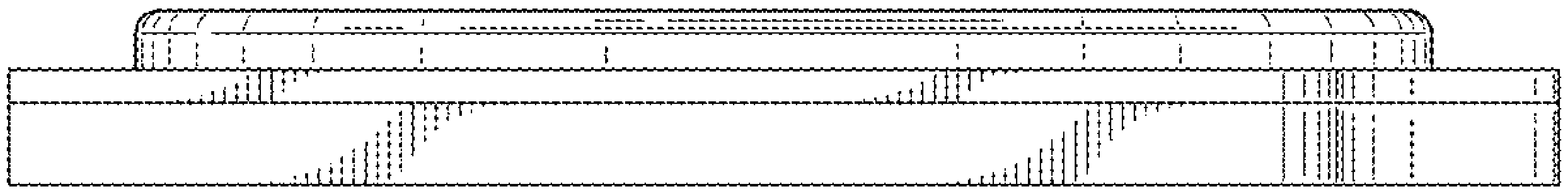

FIG. 11

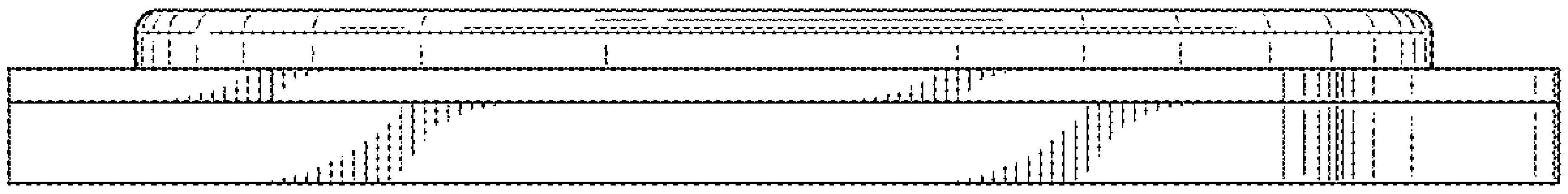

FIG. 12